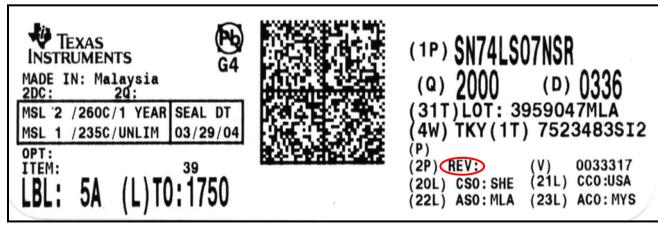
PCN Number:		20140410000							PCN Date:		04/14/2014
Title: Design Revision (NBTI Fix for Select TPS40055x Devices)											
Customer Contact:		PCN /	Manage	<u>Phor</u>	ne:	e: +1(214)480-6037			Dept:	Quality Services	
Proposed 1 st Ship Da		07/14/2014			Estimated			Sample Date provide		e provided at	
		te:	07/14/2014		Ava		vail	ilability: sar		nple request	
Change Type:											
Asse		Assembly Pro			ocess			Assembly Materials			
Design			Electrical Specification				_	Mechanical Specification			
Test		Packing/Shipping/Labeling					Test Process				
Wafe		Wafer Bump Material				_	Wafer Bump Process				
Wafe	Wafer Fab Site Wafer Fab							\	Wafer Fab Process		
			Part number change								
PCN Details											
Descrip	tion of Chang	e:									
This notification is to inform of a design revision for select TPS40055x devices. This design change does not affect the device's guaranteed datasheet specifications or electrical performance. The affected devices are listed in the "Product Affected" section. The table below describes changes that were made: Description of Change Re-design to remove sensitivity over time to negative bias temperature instability (NBTI) under high temperature conditions. Improve reliability											
Reason for Change:											
.	reliability										
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Changes to product identification resulting from this PCN:											
Die Rev designator will change as shown in table & sample label below: Current New Die Rev [2P] Die Rev [2P] A C											

Sample product shipping label to indicate die rev location (**not actual product label**)



Product Affected:								
MPL2674QPWPR TPS40055MPWP			TPS40055MPWPREF	62/05617-01XE				
	Qualification D	ata:	Approved 2/14	/2014				
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.								
Qual Vehicle 1: TPS40055PWP								
	Package/	Die Co	nstruction Details					
Assembly Site: TI TAIWAN			s-Designator, Family:	P, HTSSOP				
Fab Process: LBC4			Die Revision:					
Qualification: Plan Test Results								
Reliability Test			ditions	Sample Size (PASS/FAIL)				
Electrical Characterization, side by side			Datasheet Parameter	Pass				
Qual Vehicle 2: TPS40057PWP								
	Package/	Die Co	nstruction Details					
Assembly Site: TI TAIWAN			s-Designator, Family:	16-PWF	P, HTSSOP			
Fab Process: LBC4			Die Revision:					
Qualification:								
Reliability Test			ditions	Sample Size (PASS/FAIL)				
Latch-up			JESD78)	6/0				
Electrical Characterization, side by side			Datasheet Parameter	Pass				
High Temp Operating	Life	125	C (1000 Hrs)	80/0				
ESD HBM			0V	3/3 **				
ESD CDM		250	V	3/0				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

^{**} This device fails ESD-HBM due to leakage on the SW pin. The device was released in 2004 with an HBM rating of 1KV. Several SW leakage tests were added to the final test program since RTM. The new SW leakage tests are failing now both on the old and new die rev.